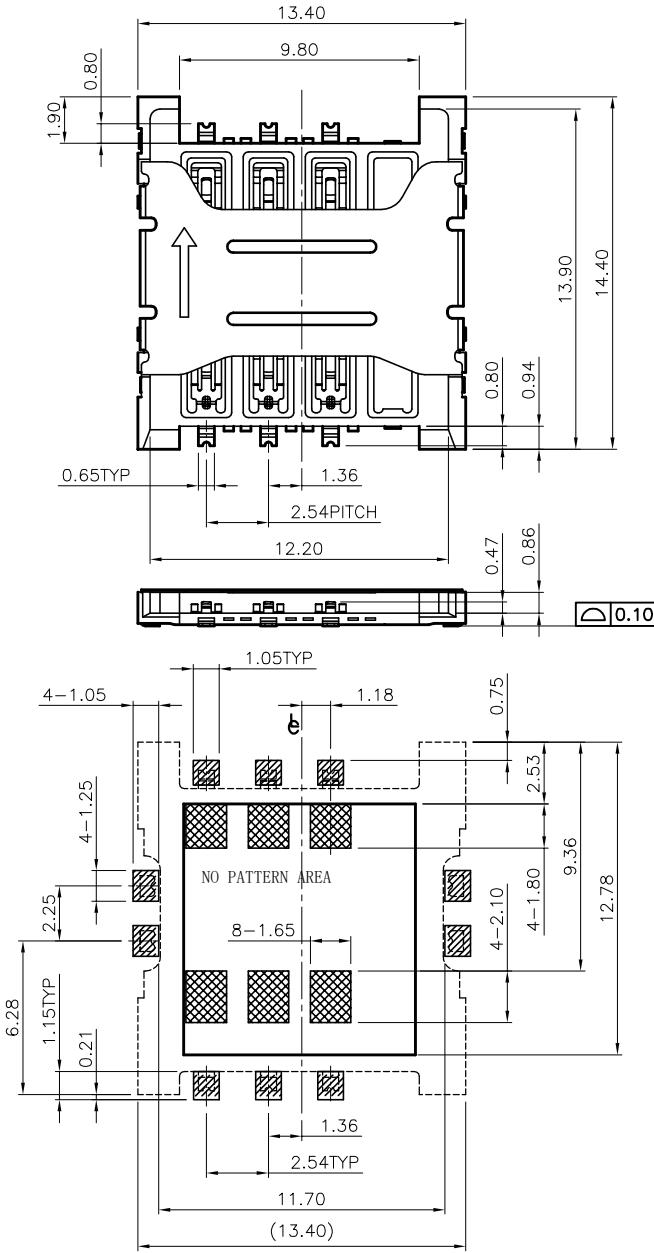
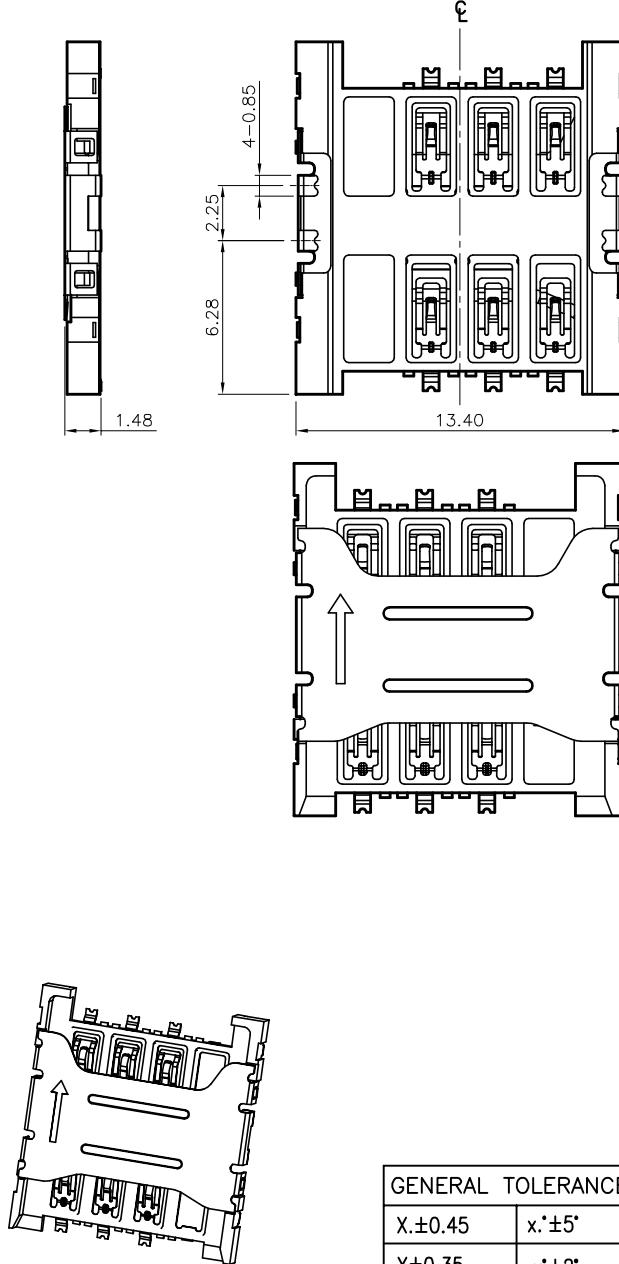


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2011/10/31



RECOMMENDED P.C.B. LAYOUT  
TOLERANCE:  $\pm 0.05$  TOP VIEW

PCB AREA  
CONNECT AREA  
KEEP OUT AREA



## MATERIALS

1. HOUSING : THERMOPLASTIC (UL 94V-0) .
2. TERMINAL : COPPER ALLOY,  
PLATING : GOLD PLATED ON CONTACT AREA  
AND SOLDER TAILS, NICKEL PLATED OVERALL.
3. SHELL : STAINLESS STEEL.  
PLATING : NICKEL PLATED OVERALL.  
GOLD PLATED ON SOLDER TAILS

## SPECIFICATION

1. CURRENT RATING : 1.0 A MAX.
2. DIELECTRIC WITHSTANDING VOLTAGE :  
500V AC R.M.S. FOR ONE MINUTE.
3. INSULATION RESISTANCE : 1000M<sup>2</sup> MIN. AT 500V DC.
4. CONTACT RESISTANCE : 30m $\Omega$  MAX.
5. OPERATING TEMPERATURE : -40°C TO +85°C.

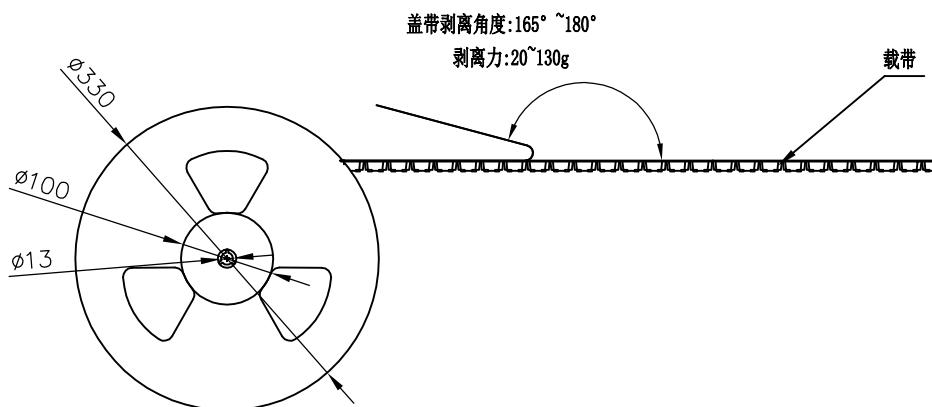
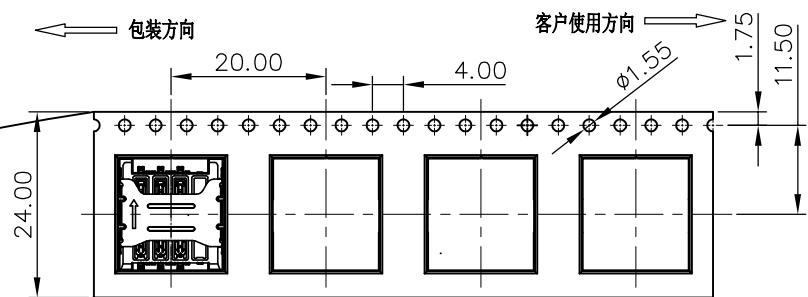
## DESCRIPTION OF PLATING ON TERMINALS

NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15 $\mu$ "
1	GOLD 5 $\mu$ "	4	GOLD 20 $\mu$ "
2	GOLD 10 $\mu$ "	6	GOLD 30 $\mu$ "

GENERAL TOLERANCE		DWG NO.			APPD:	WIND	Scale	1:1
X. $\pm 0.45$	x. $\pm 5^\circ$	Title	MICRO SIM SOCKET 6PIN 1.50H (焊接脚内折防滑PIN)		CHKD:		UNIT	mm
.X $\pm 0.35$	.x. $\pm 2^\circ$				DR:			
.XX $\pm 0.25$	.xx. $\pm 1^\circ$	Part NO.	5001B-SIM150-090		Date	2012/02/29		
.XXX $\pm 0.15$	.xxx. $\pm 0.5^\circ$							
SHEET	1/1							

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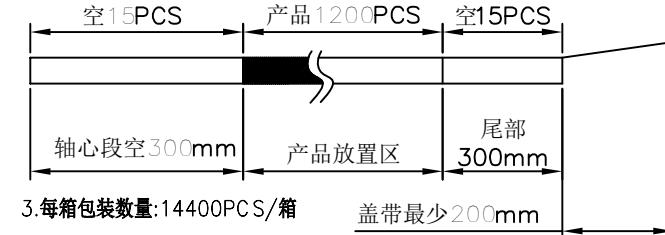
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2012/04/13



### NOTES

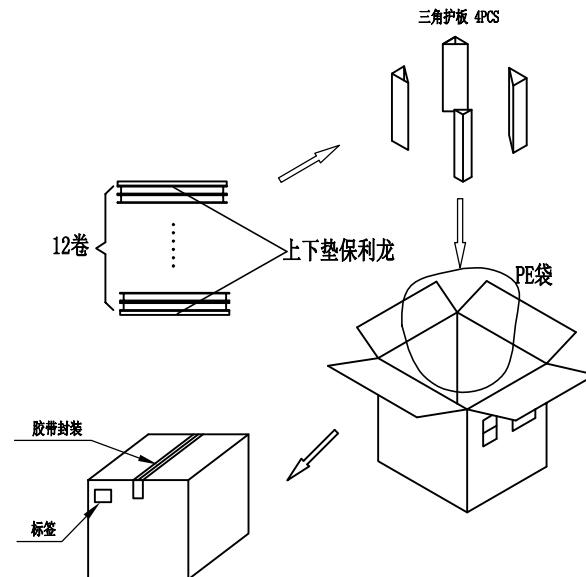
1. 每卷包装数量: 1200PCS / 每卷

2. 卷带包装方式:



3. 每箱包装数量: 14400PCS / 箱

4. 纸箱规格: 340\*340\*390MM, 材质: K=K



GENERAL TOLERANCE		DWG NO.	5001B-SIM150-090	APPD:	WIND	Scale	1:1
X.±0.45	x.±5°	Title	MICRO SIM CARD 6P 1.5H 包装图	CHKD:		UNIT	mm
.X±0.35	.x.±2°			DR:			
.XX±0.25	.xx.±1°	Part NO.		Date	2012/04/13		
.XXX±0.15	.xxx.±0.5°						
SHEET	1/1						

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